



Material Content Data Sheet



Sales Product Name		TLE8108EM		Issued		26. September 2017		
MA#		MA000969214						
Package		PG-SSOP-24-4		Weight*		150.67 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.956	1.96	1.96	19620	19620
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		112	
	non noble metal	zinc	7440-66-6	0.067	0.04		446	
	non noble metal	iron	7439-89-6	1.345	0.89		8927	
wire	non noble metal	copper	7440-50-8	54.617	36.25	37.19	362490	371975
	noble metal	gold	7440-57-5	0.575	0.38	0.38	3817	3817
	encapsulation	organic material	carbon black	1333-86-4	0.174	0.12		1155
plastics	plastics	epoxy resin	-	8.003	5.31		53119	
	inorganic material	silicondioxide	60676-86-0	78.817	52.31	57.74	523103	577377
	leadfinish	non noble metal	tin	7440-31-5	2.947	1.96	1.96	19561
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1555	1555
glue	plastics	epoxy resin	-	0.230	0.15		1524	
	noble metal	silver	7440-22-4	0.689	0.46	0.61	4571	6095
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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